FC5516010R Dual N-channel MOSFET

For switching

Features

• Low drive voltage: 2.5 V drive

- Halogen-free / RoHS compliant
- (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: V5

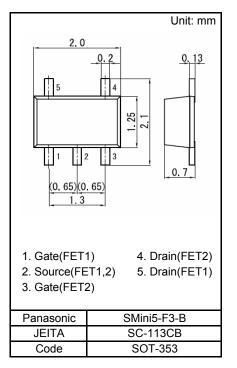
■ Basic Part Number Dual FK350601 (Source Common type)

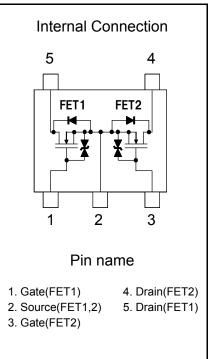
Packaging

FC5516010R Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter		Symbol	Rating	Unit	
	Drain-source Voltage	VDS	60	V	
	Gate-source Voltage	VGS	±12	V mA	
	Drain current	ID	100		
	Drain current (Pulsed)	IDp	200	mA	
Overall	Total power dissipation	PD	150	mW	
	Channel temperature	Tch	150	°C	
	Storage temperature	Tstg	-55 to +150	°C	





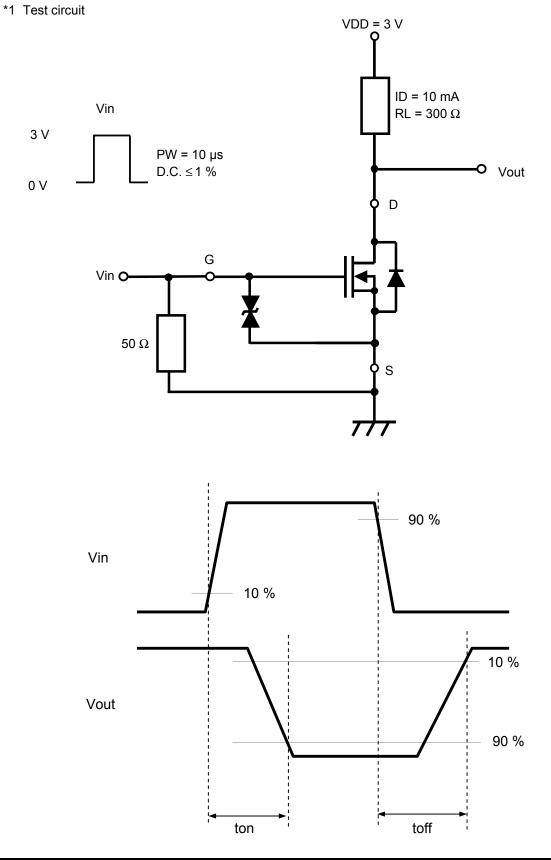
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Electrical Characteristics	Ta = 25 °C ± 3 °C
FET1,FET2	

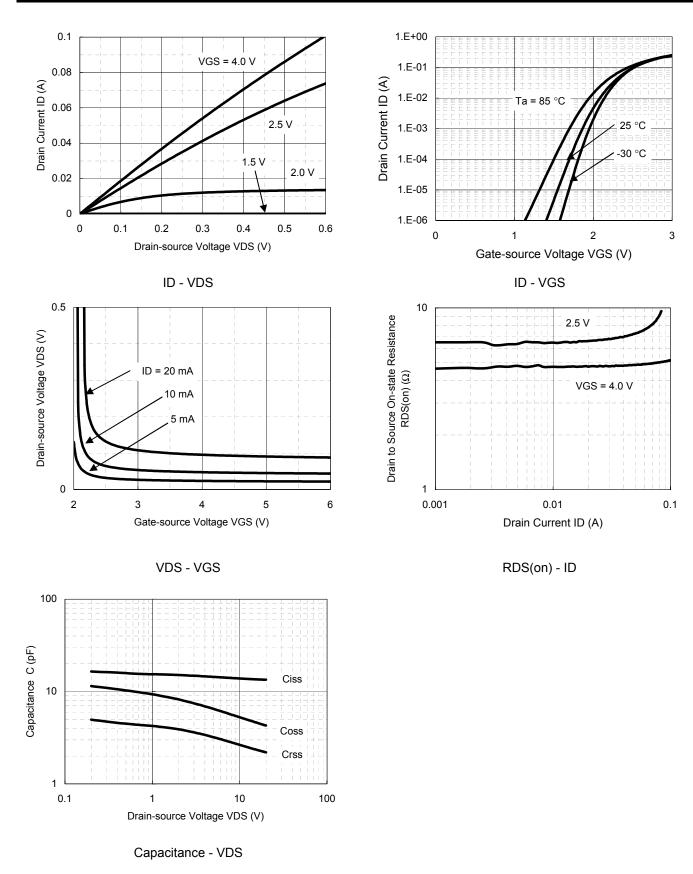
Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Drain-source Breakdown Voltage	VDSS	ID = 1.0 mA, VGS = 0 V	60			V	
Zero Gate Voltage Drain Current	IDSS	VDS = 60 V, VGS = 0 V			1.0	μA	
Gate-source Leakage Current	IGSS	VGS = ±10 V, VDS = 0 V			±10	μA	
Gate-source Threshold Voltage	Vth	ID = 1.0 μA, VDS = 3.0 V	0.9	1.2	1.5	V	
Drain-source On-state Resistance	RDS(on)1	ID = 10 mA, VGS = 2.5 V		8	15	Ω	
Dialit-source Off-state Resistance	RDS(on)2	ID = 10 mA, VGS = 4.0 V		6	12	52	
Forward transfer admittance	Yfs	ID = 10 mA, VDS = 3.0 V	20	60		mS	
Input Capacitance	Ciss			12		pF	
Output Capacitance	Coss	VDS = 3 V, VGS = 0 V, f = 1 MHz		7			
Reverse Transfer Capacitance	Crss			3			
Turn-on time ^{*1}	ton	VDD = 3 V, VGS = 0 V to 3 V ID = 10 mA		100		ns	
Turn-off time ^{*1}	toff	VDD = 3 V, VGS = 3 V to 0 V ID = 10 mA		100		ns	

Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

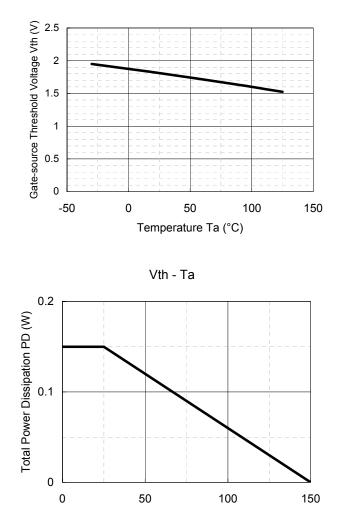
*1 See Test circuit



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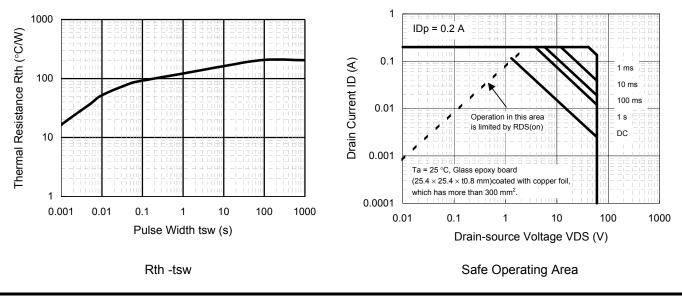


12 Drain-source On-state Resistance 10 2.5 V 8 RDS(on) (Ω) VGS = 4.0 V 6 4 2 0 -50 0 50 150 200 100 Temperature Ta (°C)

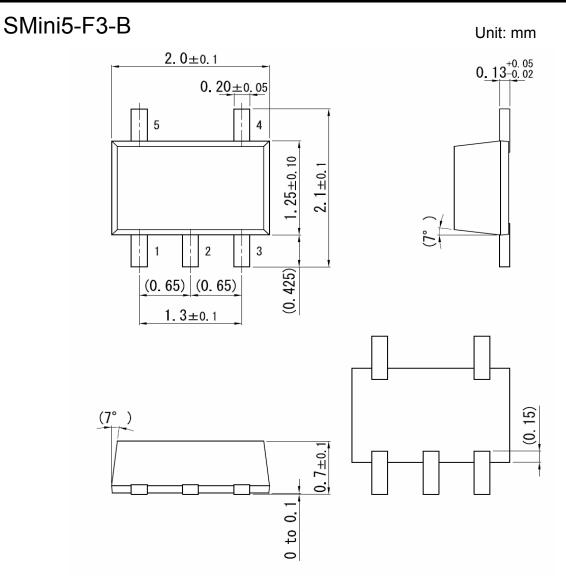




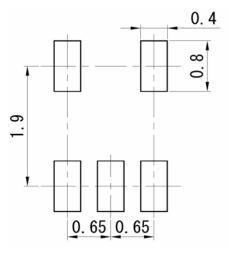
Temperature Ta (°C)



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■ Land Pattern (Reference) (Unit: mm)



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